

Title (en)  
FLEXIBLE CONTINUOUS CATHODE CONTACT CIRCUIT FOR ELECTROLYTIC PLATING OF C4, TAB MICROBUMPS, AND ULTRA LARGE SCALE INTERCONNECTS

Title (de)  
FLEXIBLE KONTINUIERLICHE KATHODENSCHALTUNG FÜR DIE ELEKTROLYTISCHE BESCHICHTUNG VON C4, TAB MICROBUMP UND SCHALTUNGEN IM ULTRAGROSSMASSSTAB

Title (fr)  
CIRCUIT SOUPLE CONTINU DE CATHODE DE CONTACT POUR PLACAGE ELECTROLYTIQUE DE MICROPLOTS C4 ET TAB ET D'INTERCONNEXIONS A TRES HAUTE ECHELLE

Publication  
**EP 0859877 B1 20040526 (EN)**

Application  
**EP 96931651 A 19960919**

Priority  
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• US 53448995 A 19950927

Abstract (en)  
[origin: US5871626A] A cathode contact device is provided for providing particle deposition from an anode source onto a target surface of a working piece. The working piece has a first electrically conductive continuous contact surrounding the target surface. The cathode contact device includes a second electrically conductive continuous contact adapted for frictionally contacting the first contact along a continuous path located on the first contact. The second contact further has an inner periphery defining an aperture for passing therethrough the particles onto the target surface. Additionally, the cathode contact device includes a circuit for electrically coupling the second contact to an electrical current supply.

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IPC 8 full level  
**C25D 5/02** (2006.01); **C25D 7/12** (2006.01); **C25D 17/06** (2006.01); **H01L 21/60** (2006.01)

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